

APPENDIX A
“CLEAN” VERSION OF EACH PARAGRAPH/SECTION/CLAIM
37 C.F.R. § 1.121(b)(ii) AND (c)(i)

SPECIFICATION:

Paragraph at page 2, line 4 to page 2, line 5:

On the other hand, the method shown in Fig. 13 includes a step of heating a nonreciprocal circuit device in the assembling process to slightly demagnetize (anneal) the magnet.

Paragraph at page 2, line 6 to page 2, line 7:

Fig. 13 is a flowchart showing the process of manufacturing the nonreciprocal circuit device including the heating step.

Paragraph at page 2, line 8 to page 2, line 10:

In this process, as shown in Fig. 13, the nonreciprocal circuit device is heated after being assembled to perform partial thermal demagnetization of the magnet. This arrangement can prevent the deterioration of characteristics due to thermal demagnetization after the device is manufactured and sold.

Paragraph at page 5, line 21 to page 6, line 3:

As shown in Fig. 1, the assembly of all components forming the nonreciprocal circuit device, which include a metal case, is completed in an assembly process, and then the electrical and mechanical junctions of the components are soldered to finish the entire structure. After that, the magnetic force of a magnet is adjusted, and then, a thermosetting resin is applied on an outer surface of the metal case. Next, heat is applied to thermally demagnetize (anneal) the magnet and harden the resin at the same time.

Paragraph at page 6, line 7 to page 6, line 9:

In addition, the resin may be applied before adjusting the magnetic force. However, immediately after the application, the resin needs to be temporarily hardened. Otherwise, the resin will flow out and adhere unnecessarily to other parts and to manufacturing machinery.

APPENDIX B
VERSION WITH MARKINGS TO SHOW CHANGES MADE
37 C.F.R. § 1.121(b)(iii) AND (c)(ii)

SPECIFICATION:

Paragraph at page 2, line 4 to page 2, line 5:

On the other hand, the method shown in Fig. 13 includes a step of heating a nonreciprocal circuit device in the assembling process to slightly demagnetize (anneal) the magnet.

Paragraph at page 2, line 6 to page 2, line 7:

Fig. 13 is a flowchart showing the process of manufacturing the nonreciprocal circuit device including [a] the heating step.

Paragraph at page 2, line 8 to page 2, line 10:

In this process, as shown in Fig. 13, the nonreciprocal circuit device is heated after being assembled to perform partial thermal demagnetization of [a] the magnet. This arrangement can prevent the deterioration of characteristics due to thermal demagnetization after [being] the device is manufactured and sold.

Paragraph at page 5, line 21 to page 6, line 3:

As shown in Fig. 1, the assembly of all components forming the nonreciprocal circuit device, which include a metal case, is completed in an assembly process, and then the electrical and mechanical junctions of the components are soldered to finish the entire structure. After that, the magnetic force of a magnet is adjusted, and then, a thermosetting resin is applied on an outer surface of the metal case. Next, heat is applied to thermally demagnetize [a] (anneal) the magnet and harden the resin at the same time.

Paragraph at page 6, line 7 to page 6, line 9:

In addition, the resin may be applied before adjusting the magnetic force. However, immediately after the application, the resin needs to be temporarily hardened. Otherwise, the resin will flow out and adhere [to unnecessary] unnecessarily to other parts and [a manufactured device] to manufacturing machinery.